# **Dual 4-Input NAND Gate**

- Outputs Source/Sink 24 mA
- 'ACT20 Has TTL Compatible Inputs

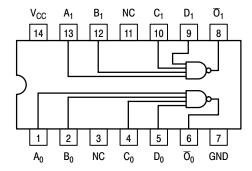


Figure 1. Pinout: 14-Lead Packages (Top View)

## **PIN ASSIGNMENT**

PIN	FUNCTION
A <sub>n</sub> , B <sub>n</sub> , C <sub>n</sub> , D <sub>n</sub>	Inputs
$\overline{O}_n$	Outputs

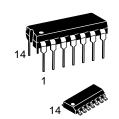
## **MAXIMUM RATINGS\***

Rating	Symbol	Value	Unit
DC Supply Voltage (Referenced to GND)	V <sub>CC</sub>	-0.5 to +7.0	V
DC Input Voltage (Referenced to GND)	V <sub>in</sub>	$-0.5 \text{ to} \\ V_{CC} + 0.5$	V
DC Output Voltage (Referenced to GND)	V <sub>out</sub>	-0.5  to  V <sub>CC</sub> + 0.5	V
DC Input Current, per Pin	I <sub>in</sub>	± 20	mA
DC Output Sink/Source Current, per Pin	I <sub>out</sub>	± 50	mA
DC V <sub>CC</sub> or GND Current per Output Pin	Icc	± 50	mA
Storage Temperature	T <sub>stg</sub>	-65 to +150	°C

<sup>\*</sup>Maximum Ratings are those values beyond which damage to the device may occur. Functional operation should be restricted to the Recommended Operating Conditions.



http://onsemi.com



PDIP-14 N SUFFIX CASE 646

SO-14 D SUFFIX CASE 751A



TSSOP-14 DT SUFFIX CASE 948G



EIAJ-14 M SUFFIX CASE 965

#### ORDERING INFORMATION

J. J								
Device	Package	Shipping						
MC74AC20N	PDIP-14	25 Units/Rail						
MC74ACT20N	PDIP-14	25 Units/Rail						
MC74AC20D	SOIC-14	55 Units/Rail						
MC74AC20DR2	SOIC-14	2500 Tape & Reel						
MC74ACT20D	SOIC-14	55 Units/Rail						
MC74ACT20DR2	SOIC-14	2500 Tape & Reel						
MC74AC20DT	TSSOP-14	96 Units/Rail						
MC74AC20DTR2	TSSOP-14	2500 Tape & Reel						
MC74ACT20DT	TSSOP-14	96 Units/Rail						
MC74ACT20DTR2	TSSOP-14	2500 Tape & Reel						
MC74AC20M	EIAJ-14	50 Units/Rail						
MC74AC20MEL	EIAJ-14	2000 Tape & Reel						
MC74ACT20MEL	EIAJ-14	2000 Tape & Reel						

# **DEVICE MARKING INFORMATION**

See general marking information in the device marking section on page 5 of this data sheet.

## RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Тур	Min	Unit
V	Complex Valtage	'AC	2.0	5.0	6.0	V
V <sub>CC</sub>	CC Supply Voltage	'ACT	4.5	5.0	5.5	V
VREG	DC Regulated Power Voltage (Ref. to GND)		0	-	V <sub>CC</sub>	V
		V <sub>CC</sub> @ 3.0 V	-	150	-	
t <sub>r</sub> , t <sub>f</sub>	t <sub>r</sub> , t <sub>f</sub> Input Rise and Fall Time (Note 1)  'AC Devices except Schmitt Inputs	V <sub>CC</sub> @ 4.5 V	-	40	-	ns/V
		V <sub>CC</sub> @ 5.5 V	-	25	-	
	Input Rise and Fall Time (Note 2)	V <sub>CC</sub> @ 4.5 V	-	10	-	\/
t <sub>r</sub> , t <sub>f</sub>	'ACT Devices except Schmitt Inputs	V <sub>CC</sub> @ 5.5 V	-	8.0	-	ns/V
TJ	Junction Temperature (PDIP)		-	-	140	°C
T <sub>A</sub>	Operating Ambient Temperature Range		-40	25	85	°C
I <sub>OH</sub>	Output Current – HIGH		-	-	-24	mA
I <sub>OL</sub>	Output Current – LOW		-	-	24	mA

<sup>1.</sup>  $V_{in}$  from 30% to 70%  $V_{CC}$ ; see individual Data Sheets for devices that differ from the typical input rise and fall times. 2.  $V_{in}$  from 0.8 V to 2.0 V; see individual Data Sheets for devices that differ from the typical input rise and fall times.

# **DC CHARACTERISTICS**

			74	AC	74AC		
Symbol	Parameter	V <sub>CC</sub> (V)	T <sub>A</sub> =	T <sub>A</sub> = +25°C		Unit	Conditions
			Тур	Guar	anteed Limits		
V <sub>IH</sub>	Minimum High Level Input Voltage	3.0 4.5 5.5	1.5 2.25 2.75	2.1 3.15 3.85	2.1 3.15 3.85	V	V <sub>OUT</sub> = 0.1 V or V <sub>CC</sub> – 0.1 V
V <sub>IL</sub>	Maximum Low Level Input Voltage	3.0 4.5 5.5	1.5 2.25 2.75	0.9 1.35 1.65	0.9 1.35 1.65	V	V <sub>OUT</sub> = 0.1 V or V <sub>CC</sub> – 0.1 V
V <sub>OH</sub>	Minimum Low Level Output Voltage	3.0 4.5 5.5	2.99 4.49 5.49	2.9 4.4 5.4	2.9 4.4 5.4	V	$I_{OUT} = -50 \mu A$
		3.0 4.5 5.5		2.56 3.86 4.86	2.46 3.76 4.76	V	$^{*}V_{IN} = V_{IL} \text{ or } V_{IH}$ $- 12 \text{ mA}$ $I_{OH} - 24 \text{ mA}$ $- 24 \text{ mA}$
V <sub>OL</sub>	Maximum Low Level Output Voltage	3.0 4.5 5.5	0.002 0.001 0.001	0.1 0.1 0.1	0.1 0.1 0.1	V	I <sub>OUT</sub> = 50 μA
		3.0 4.5 5.5	- - -	0.36 0.36 0.36	0.44 0.44 0.44	V	$^*$ V <sub>IN</sub> = V <sub>IL</sub> or V <sub>IH</sub> 12 mA I <sub>OL</sub> 24 mA 24 mA
I <sub>IN</sub>	Maximum Input Leakage Current	5.5	_	±0.1	±1.0	μΑ	$V_I = V_{CC}$ , GND
I <sub>OLD</sub>	†Minimum Dynamic	5.5	_	_	75	mA	V <sub>OLD</sub> = 1.65 V Max
I <sub>OHD</sub>	Output Current	5.5	-	-	<del>-</del> 75	mA	V <sub>OHD</sub> = 3.85 V Min
Icc	Maximum Quiescent Supply Current	5.5	_	4.0	40	μΑ	$V_{IN} = V_{CC}$ or GND

<sup>\*</sup>All outputs loaded; thresholds on input associated with output under test.

NOTE:  $I_{IN}$  and  $I_{CC}$  @ 3.0 V are guaranteed to be less than or equal to the respective limit @ 5.5 V.

<sup>†</sup>Maximum test duration 2.0 ms, one output loaded at a time.

# **AC CHARACTERISTICS**

			74AC			74AC		
Symbol	Parameter	V <sub>CC</sub> * (V)					35°C	Unit
		'	Min	Тур	Max	Min	Max	
t <sub>PLH</sub>	Propagation Delay	3.3 5.0	2.0 1.5	6.0 5.0	8.5 7.0	1.5 1.0	10.0 8.0	ns
t <sub>PHL</sub>	Propagation Delay	3.3 5.0	1.5 1.5	5.0 4.0	7.0 6.0	1.0 1.0	9.0 7.0	ns

<sup>\*</sup>Voltage Range 3.3 V is 3.3 V  $\pm 0.3$  V. Voltage Range 5.0 V is 5.0 V  $\pm 0.5$  V.

# **DC CHARACTERISTICS**

			74	CT	74ACT		
Symbol	Parameter $V_{CC}$ $(V)$ $T_A = +25^{\circ}C$		T <sub>A</sub> = -40°C to +85°C	Unit	Conditions		
			Тур	Guar	anteed Limits		
V <sub>IH</sub>	Minimum High Level Input Voltage	4.5 5.5	1.5 1.5	2.0 2.0	2.0 2.0	٧	V <sub>OUT</sub> = 0.1 V or V <sub>CC</sub> – 0.1 V
V <sub>IL</sub>	Maximum Low Level Input Voltage	4.5 5.5	1.5 1.5	0.8 0.8	0.8 0.8	٧	V <sub>OUT</sub> = 0.1 V or V <sub>CC</sub> – 0.1 V
V <sub>OH</sub>	Minimum High Level Output Voltage	4.5 5.5	4.49 5.49	4.4 5.4	4.4 5.4	٧	I <sub>OUT</sub> = - 50 μA
		4.5 5.5	_ _	3.86 4.86	3.76 4.76	V	$^*V_{IN} = V_{IL} \text{ or } V_{IH}$ $-24 \text{ mA}$ $-24 \text{ mA}$
V <sub>OL</sub>	Maximum Low Level Output Voltage	4.5 5.5	0.001 0.001	0.1 0.1	0.1 0.1	٧	I <sub>OUT</sub> = 50 μA
		4.5 5.5	_ _	0.36 0.36	0.44 0.44	V	*V <sub>IN</sub> = V <sub>IL</sub> or V <sub>IH</sub> 24 mA I <sub>OH</sub> 24 mA
I <sub>IN</sub>	Maximum Input Leakage Current	5.5	_	±0.1	±1.0	μΑ	$V_I = V_{CC}$ , GND
$\Delta I_{CCT}$	Additional Max. I <sub>CC</sub> /Input	5.5	0.6	-	1.5	mA	$V_{I} = V_{CC} - 2.1 \text{ V}$
I <sub>OLD</sub>	†Minimum Dynamic	5.5	-	-	75	mA	V <sub>OLD</sub> = 1.65 V Max
I <sub>OHD</sub>	Output Current	5.5	-	-	<b>-</b> 75	mA	V <sub>OHD</sub> = 3.85 V Min
I <sub>CC</sub>	Maximum Quiescent Supply Current	5.5	_	4.0	40	μΑ	$V_{IN} = V_{CC}$ or GND

<sup>\*</sup>All outputs loaded; thresholds on input associated with output under test. †Maximum test duration 2.0 ms, one output loaded at a time.

# **AC CHARACTERISTICS**

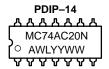
			74ACT			74ACT		
Symbol	Parameter	V <sub>CC</sub> * (V)					Unit	
			Min	Тур	Max	Min	Max	
t <sub>PLH</sub>	Propagation Delay	5.0	2.0	6.5	9.0	1.5	10.5	ns
t <sub>PHL</sub>	Propagation Delay	5.0	2.0	5.5	9.0	1.5	10.5	ns

<sup>\*</sup>Voltage Range 5.0 V is 5.0 V  $\pm 0.5$  V.

# CAPACITANCE

Symbol	Parameter	Value Typ	Unit	Test Conditions
C <sub>IN</sub>	Input Capacitance	4.5	pF	V <sub>CC</sub> = 5.0 V
C <sub>PD</sub>	Power Dissipation Capacitance	40	pF	V <sub>CC</sub> = 5.0 V

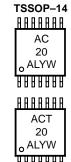
## **MARKING DIAGRAMS**

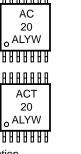












74AC20 ALYW 0 <u>יייטטטטטט</u>  $\Pi\Pi\Pi\Pi\Pi\Pi\Pi$ 74ACT20 ALYW 0 

EIAJ-14

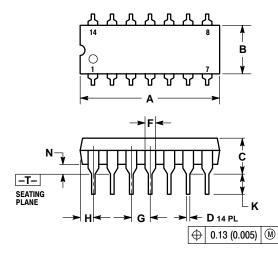
 $\overline{\mathsf{n}}$ 

= Assembly Location

WL, L = Wafer Lot YY, Y = Year WW, W = Work Week

## **PACKAGE DIMENSIONS**

# PDIP-14 **N SUFFIX** 14 PIN PLASTIC DIP PACKAGE CASE 646-06 ISSUE M





#### NOTES:

- VOIES.

  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

  2. CONTROLLING DIMENSION: INCH.

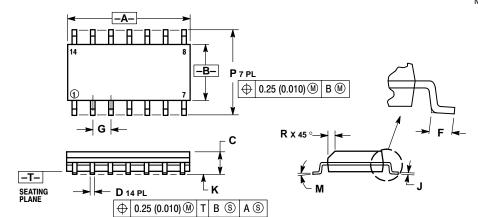
  3. DIMENSION L TO CENTER OF LEADS WHEN
- FORMED PARALLEL

  4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.

  5. ROUNDED CORNERS OPTIONAL.

	INCHES		MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.715	0.770	18.16	18.80
В	0.240	0.260	6.10	6.60
С	0.145	0.185	3.69	4.69
D	0.015	0.021	0.38	0.53
F	0.040	0.070	1.02	1.78
G	0.100	BSC	2.54 BSC	
Н	0.052	0.095	1.32	2.41
۲	0.008	0.015	0.20	0.38
K	0.115	0.135	2.92	3.43
L	0.290	0.310	7.37	7.87
M		10°		10°
N	0.015	0.039	0.38	1.01

# SO-14 **D SUFFIX** 14 PIN PLASTIC SOIC PACKAGE CASE 751A-03 ISSUE F



## NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 114.3M, 1992.

  CONTROLLING DIMENSION: MILLIMETER.

  DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.

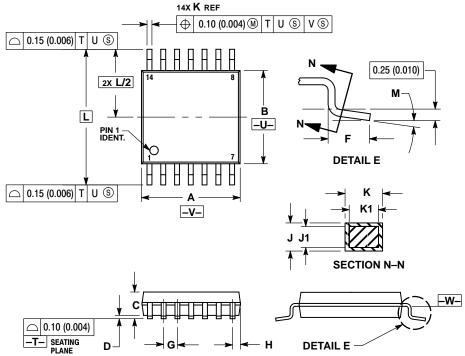
  MAXIMUM MOLD PROTRUSION 0.15 (0.006)
- 4. MAXIMUM MOLD PHOTHUSION 9.10 (9.000)
  PER SIDE.
  5. DIMENSION D DOES NOT INCLUDE DAMBAR
  PROTRUSION. ALLOWABLE DAMBAR
  PROTRUSION SHALL BE 0.127 (0.005) TOTAL
  IN EXCESS OF THE D DIMENSION AT
  MAXIMUM MATERIAL CONDITION.

	MILLIN	IETERS	INC	HES	
DIM	MIN	MAX	MIN	MAX	
Α	8.55	8.75	0.337	0.344	
В	3.80	4.00	0.150	0.157	
С	1.35	1.75	0.054	0.068	
D	0.35	0.49	0.014	0.019	
F	0.40	1.25	0.016	0.049	
G	1.27	BSC	0.050	BSC	
J	0.19	0.25	0.008	0.009	
K	0.10	0.25	0.004	0.009	
M	0°	7°	0°	7°	
P	5.80	6.20	0.228	0.244	
R	0.25	0.50	0.010	0.019	

## PACKAGE DIMENSIONS

## TSSOP-14 **DT SUFFIX**

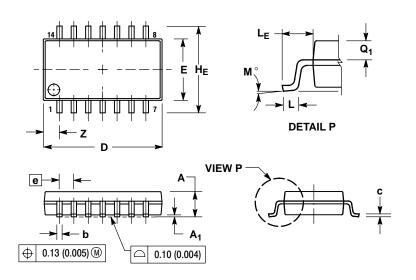
14 PIN PLASTIC TSSOP PACKAGE CASE 948G-01 **ISSUE O** 



- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: MILLIMETER.
  DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15
- (0.006) PER SIDE.
  DIMENSION B DOES NOT INCLUDE INTERLEAD
  FLASH OR PROTRUSION. INTERLEAD FLASH OR
  PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
  DIMENSION K DOES NOT INCLUDE DAMBAR
- DIMENSION K DOES NOT INCLUDE DAMBAR
  PROTRUSION. ALLOWABLE DAMBAR
  PROTRUSION. SHALL BE 0.08 (0.003) TOTAL IN
  EXCESS OF THE K DIMENSION AT MAXIMUM
  MATERIAL CONDITION.
  TERMINAL NUMBERS ARE SHOWN FOR
- REFERENCE ONLY.
  DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

	MILLIN	IETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	4.90	5.10	0.193	0.200
В	4.30	4.50	0.169	0.177
С		1.20		0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65	BSC	0.026 BSC	
Н	0.50	0.60	0.020	0.024
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40		0.252	BSC
M	0°	8°	0°	8°

# EIAJ-14 **M SUFFIX** 14 PIN PLASTIC EIAJ PACKAGE CASE 965-01 **ISSUE O**



#### NOTES:

- OTES.

  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

  2. CONTROLLING DIMENSION: MILLIMETER.
- DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
  TERMINAL NUMBERS ARE SHOWN FOR
- REFERENCE ONLY.
  THE LEAD WIDTH DIMENSION (b) DOES NOT
- INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
Α		2.05		0.081
A <sub>1</sub>	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
С	0.18	0.27	0.007	0.011
D	9.90	10.50	0.390	0.413
E	5.10	5.45	0.201	0.215
е	1.27 BSC		0.050 BSC	
HE	7.40	8.20	0.291	0.323
0.50	0.50	0.85	0.020	0.033
LE	1.10	1.50	0.043	0.059
M	0 °	10 °	0 °	10°
Q <sub>1</sub>	0.70	0.90	0.028	0.035
Z		1.42		0.056

ON Semiconductor and are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer.

#### PUBLICATION ORDERING INFORMATION

#### Literature Fulfillment

Literature Distribution Center for ON Semiconductor P.O. Box 5163, Denver, Colorado 80217 USA

**Phone**: 303–675–2175 or 800–344–3860 Toll Free USA/Canada **Fax**: 303–675–2176 or 800–344–3867 Toll Free USA/Canada

Email: ONlit@hibbertco.com

N. American Technical Support: 800-282-9855 Toll Free USA/Canada

**JAPAN**: ON Semiconductor, Japan Customer Focus Center 4–32–1 Nishi–Gotanda, Shinagawa–ku, Tokyo, Japan 141–0031

Phone: 81–3–5740–2700 Email: r14525@onsemi.com

ON Semiconductor Website: http://onsemi.com

For additional information, please contact your local

Sales Representative.